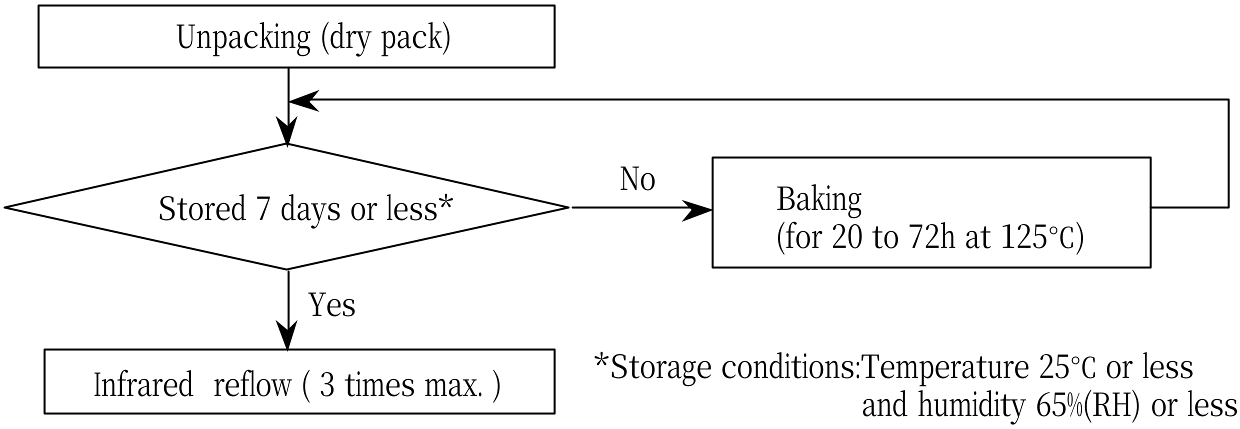
RECOMMENDED SOLDERING CONDITIONS
OF
INFRARED REFLOW
[INCLUDING CONVECTION, INFRARED/CONVECTION]

Moisture sensitive device

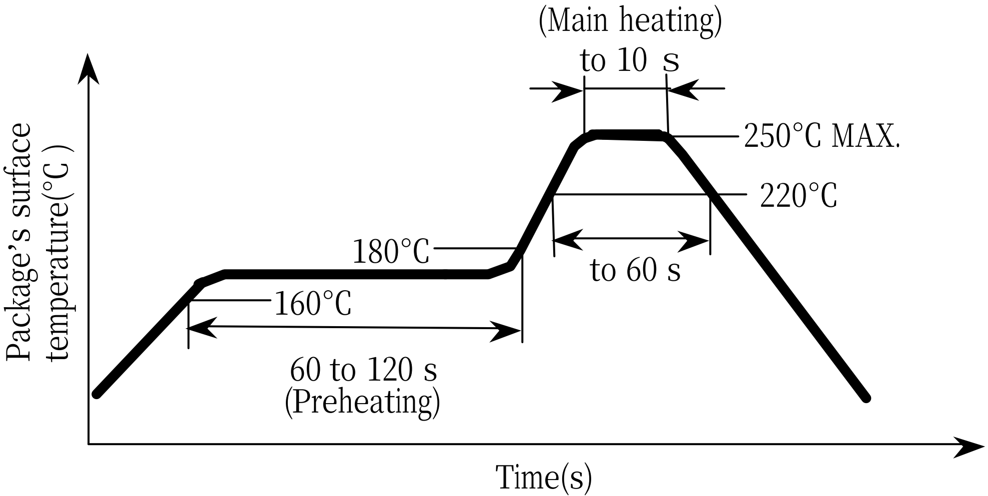
(IR50-207-3)

The following is recommended soldering conditions of infrared reflow.



*Storage conditions:Temperature 25°C or less
and humidity 65%(RH) or less

Maximum temperature (Package's surface temperature) : 250°C or below
Time at maximum temperature : 10s or less
Time of temperature higher than 220°C : 60s or less
Preheating time at 160 to 180°C : 60 to 120s
Maximum number of reflow processes : 3 times
Maximum chlorine content of rosin flux (percentage mass) : 0.2 % or less
Exposure limit (Store until the final reflow process starts) : 7 days or less



Infrared Reflow Temperature Profile

Notice

For baking components, it is necessary to use heatproof type container. Plastic magazines, emboss tape/reels and some of trays are not heatproof type, so if the packing container is not heatproof type, please transfer them to a heatproof type container.